DOWLEX™ NG 5056.01G

Polyethylene Resin

The Dow Chemical Company

Message:

DOWLEX™NG 5056.01G polyethylene resin polyethylene resin is a new generation of linear low density polyethylene resin, used for high-quality blown film processing, the processing requires a combination of excellent optical properties, tear strength and heat sealing, and very good toughness/stiffness between the balance. DOWLEX NG5056.01G polyethylene resin has a very low crystal point level, making it very suitable for composite films and other special packaging. This resin contains slip agent and opening agent.
Note: When applied to the application field of contact food, DOWLEX NG 5056.01G polyethylene resin should comply with the U.S. Food and Drug Administration when it is unmodified and the processing process follows the requirements of good manufacturing practices. The requirements of the 177.1520 regulations and the requirements of the food contact regulations of most European countries. Please contact your nearest Dow representative for proof of compliance with the Food Contact Act. The purchaser remains responsible for determining whether the use of its products complies with all relevant regulations.
Application field:
high transparency paper towel outer package
fresh food bag
food packaging film
composite film

General Information			
Additive	Anti-caking agent (2000 ppm) Sliding agent (800 ppm)		
Agency Ratings	FDA 21 CFR 177.1520		
Forms	Particle		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity [1]	0.921	g/cm³	ASTM D792
Melt Mass-Flow Rate (MFR) [2] (190°C/2.16 kg)	1.1	g/10 min	ISO 1133
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Coefficient of Friction [3] (vs. Itself - Dynamic)	0.24		ASTM D1894
Films	**Nominal Value**	**Unit**	**Test Method**
Film Thickness - Tested	50	µm	
Film Puncture Energy [4] (50 µm)	3.50	J	ASTM D5748
Film Puncture Force [5] (50 µm)	54.0	N	ASTM D5748
Tensile Modulus [6]			ISO 527-3
2% secant, MD: 50 µm	198	MPa	ISO 527-3
2% secant, TD: 50 µm	238	MPa	ISO 527-3
Tensile Stress [7]			ISO 527-3
MD: Yield, 50 µm	7.50	MPa	ISO 527-3
TD: Yield, 50 µm	8.00	MPa	ISO 527-3
MD: Break, 50 µm	38.0	MPa	ISO 527-3
TD: Break, 50 µm	37.0	MPa	ISO 527-3
Tensile Elongation [8]			ISO 527-3

MD: Break, 50 µm	810	%	ISO 527-3
TD: Break, 50 µm	920	%	ISO 527-3
Dart Drop Impact [9] (50 µm)	450	g	ISO 7765-1/A
Elmendorf Tear Strength [10]			ASTM D1922
MD : 50 µm	890	g	ASTM D1922
TD : 50 µm	1100	g	ASTM D1922
Thermal	**Nominal Value**	**Unit**	**Test Method**
Vicat Softening Temperature [11]	104	°C	ASTM D1525
Optical	**Nominal Value**	**Unit**	**Test Method**
Gloss [12] (45°, 50.0 µm)	61		ASTM D2457
Haze [13] (50.0 µm)	8.9	%	ISO 14782
Extrusion	**Nominal Value**	**Unit**	
Melt Temperature	190 - 240	°C	

Extrusion instructions

管形薄膜挤出的制造条件:
熔体温度:190 至 240°C.
放大比范围:1.5 至 3:1.
建议的厚度范围:10 至 150 µm.

NOTE

1.	Compression molding
2.	Compression molding
3.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
4.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
5.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
6.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
7.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
8.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
9.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
10.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.
11.	Compression molding
12.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.

13.	Blow molded film extruded at 235°C, 50 microns, 2.5 BUR, 1.5mm die gap.

Recommended distributors for this material

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